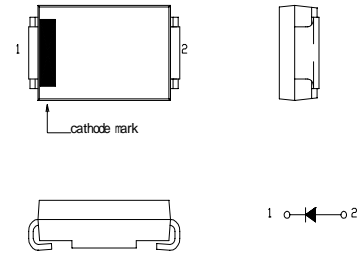


# DIODE Type : NSD03A10

OUTLINE DRAWING

構造 : 表面実装、拡散型、整流用シリコンダイオード  
 Construction: Diffusion Type Rectifier Diode  
 用途 : 一般整流用  
 Application: For General Use



## 最大定格 / Maximum Ratings

Approx Net weight:0.16g

Rating	Symbol	NSD03A10		Unit
くり返しピーク逆電圧 Repetitive Peak Reverse Voltage	$V_{RRM}$	100		V
平均整流電流 Average Rectified Output Current	$I_O$	1.57	Ta=25 *1	50Hz, 正弦半波通電 Half Sine Wave 抵抗負荷 Resistive Load
		3.0	Tl=108 *2	
実効順電流 RMS Forward Current	$I_{F(RMS)}$	4.71		A
サージ順電流 Surge Forward Current	$I_{FSM}$	80	50 Hz 正弦半波, 1サイクル, 非くり返し Half Sine Wave, 1cycle, Non-repetitive	A
動作接合温度範囲 Operating Junction Temperature Range	Tjw	- 40 ~ + 150		
保存温度範囲 Storage Temperature Range	Tstg	- 40 ~ + 150		

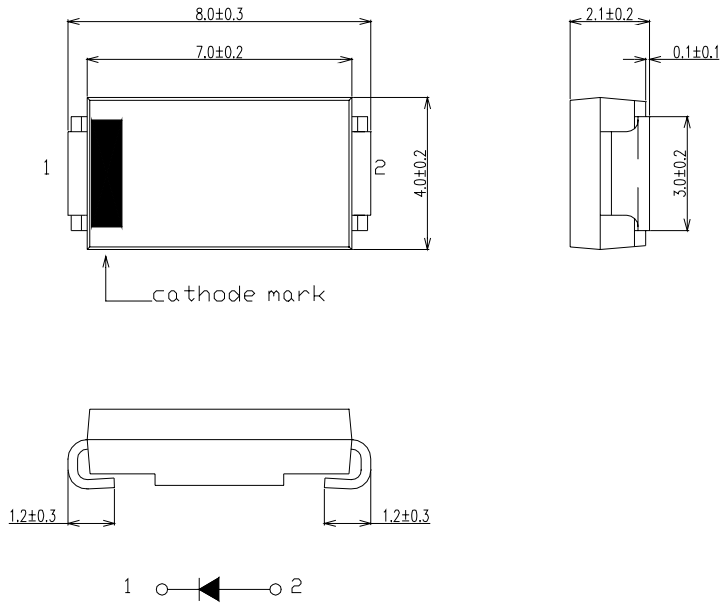
## 電氣的・熱的特性 / Electrical/Thermal Characteristics

Characteristics	Symbol	Conditions	Min.	Typ.	Max.	Unit
ピーク逆電流 Peak Reverse Current	$I_{RM}$	Tj= 25 , $V_{RM}= V_{RRM}$	-	-	50	$\mu A$
ピーク順電圧 Peak Forward Voltage	$V_{FM}$	Tj= 25 , $I_{FM}= 3.0A$	-	-	1.0	V
熱抵抗 Thermal Resistance	Rth(j-a)	接合部・周囲間 Junction to Ambient *1	-	-	89	/W
	Rth(j-l)	接合部・リード間 Junction to Lead	-	-	13	

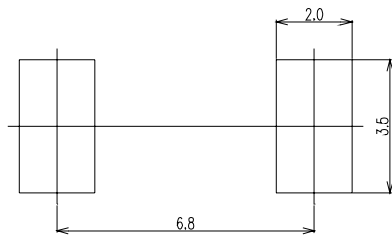
\*1:Alumina Substrate mounted (Soldering Land =2×3.5mm,Both Sides)

\*2:Tl:Lead Temperature

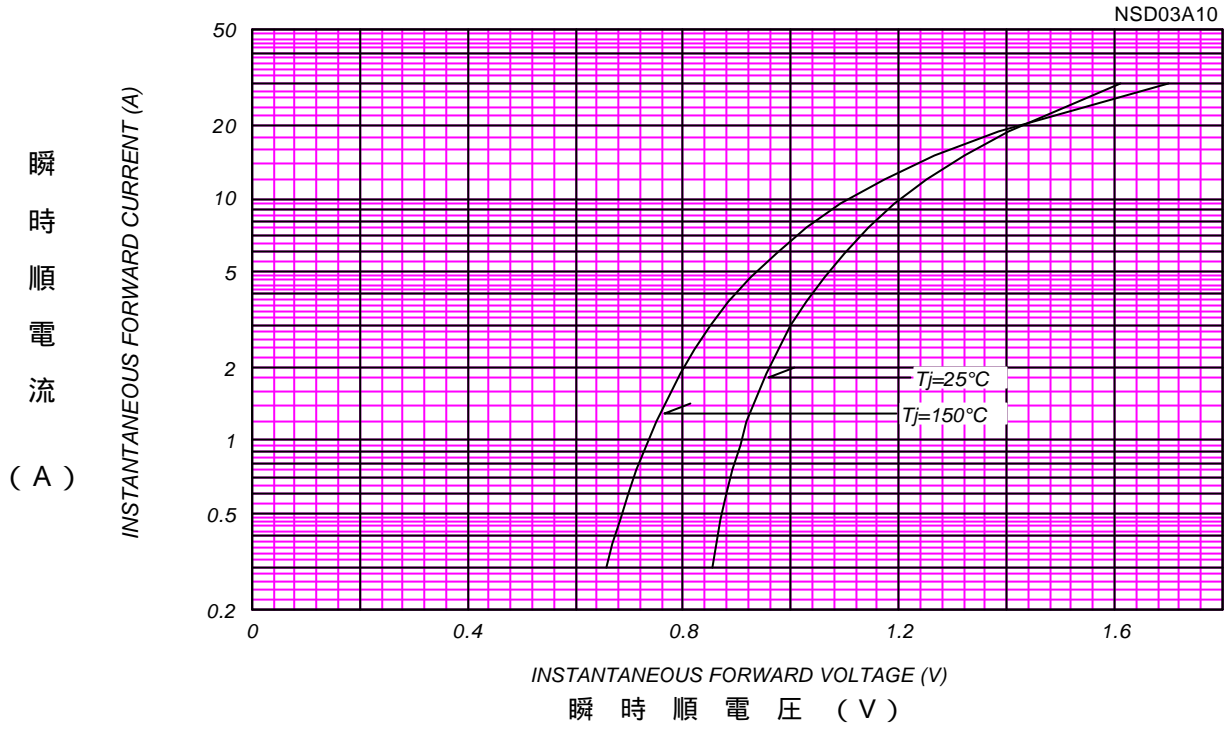
NSD03A10外形図 (mm)



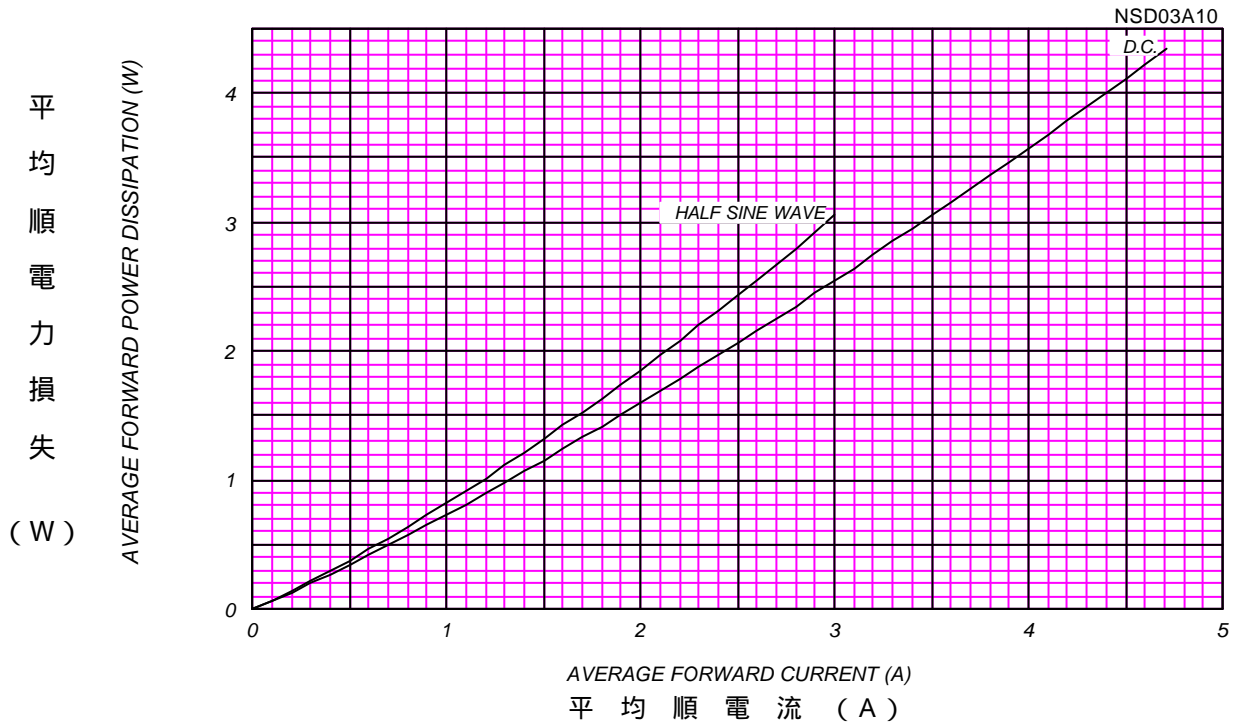
SOLDERING PAD



順電压特性  
FORWARD CURRENT VS. VOLTAGE



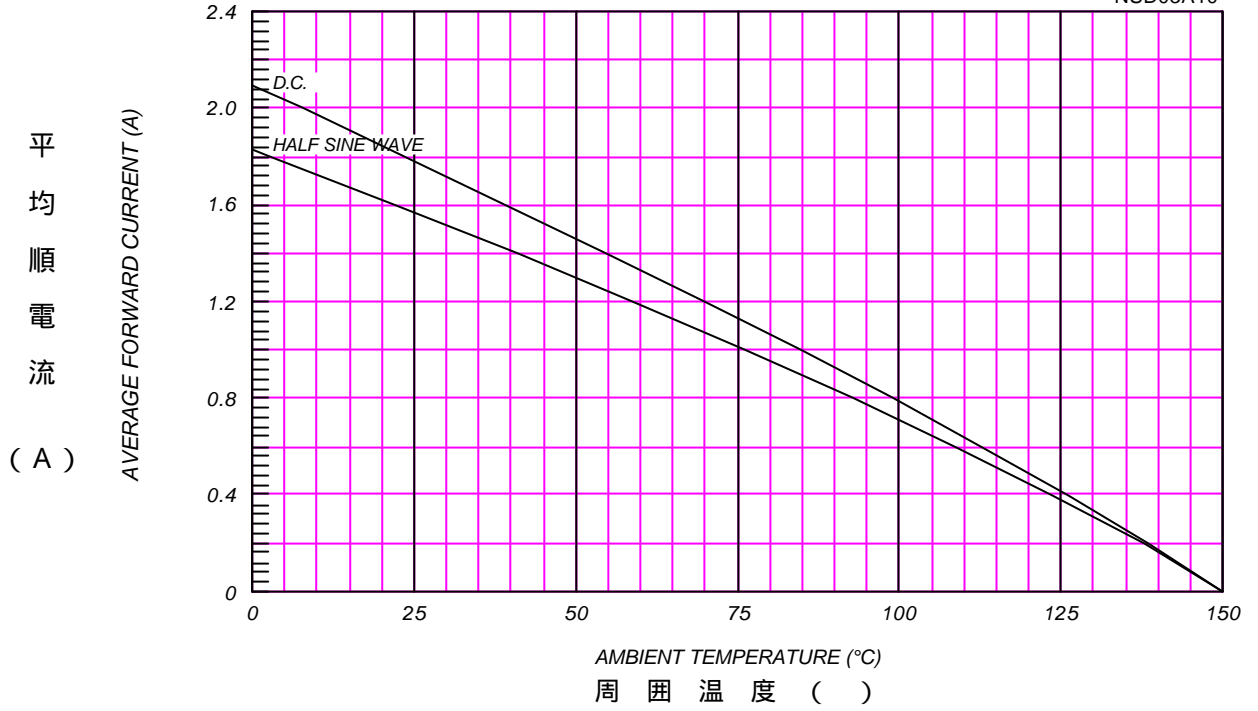
平均順電力損失特性  
AVERAGE FORWARD POWER DISSIPATION



平均順電流 - 周圍溫度定格  
AVERAGE FORWARD CURRENT VS. AMBIENT TEMPERATURE

Alumina Substrate Mounted(Soldering Land=2\*3.5mm)

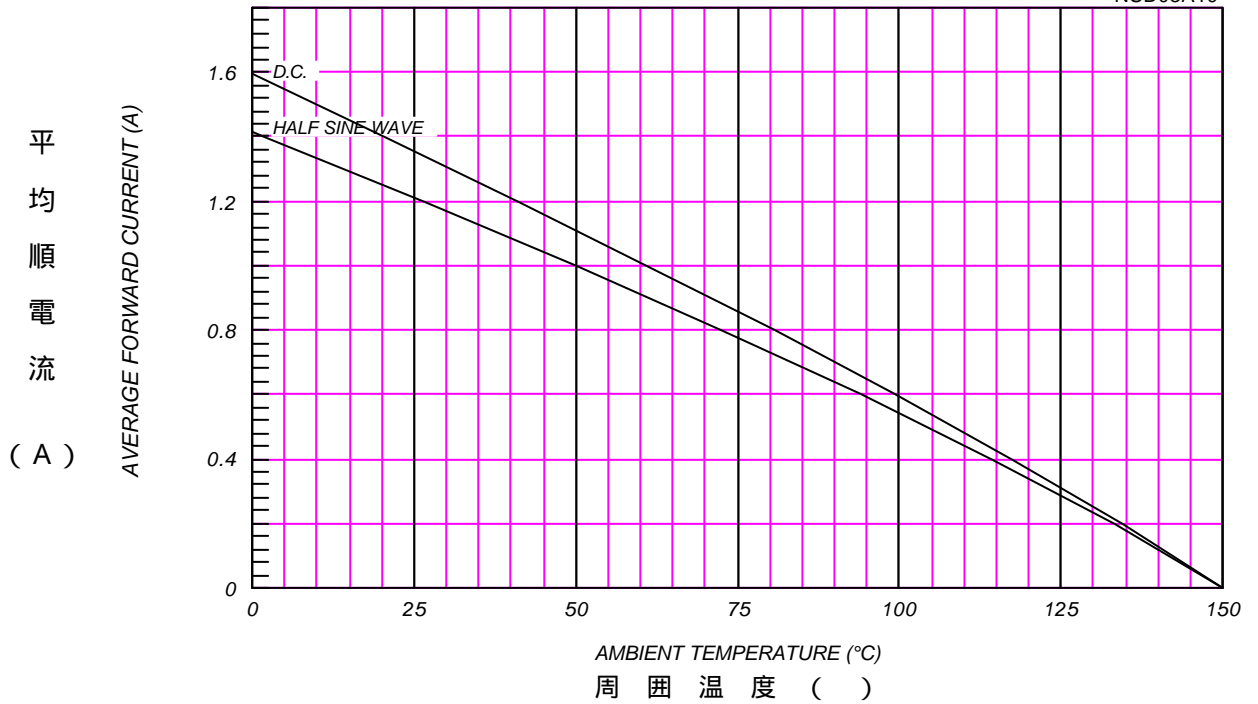
NSD03A10



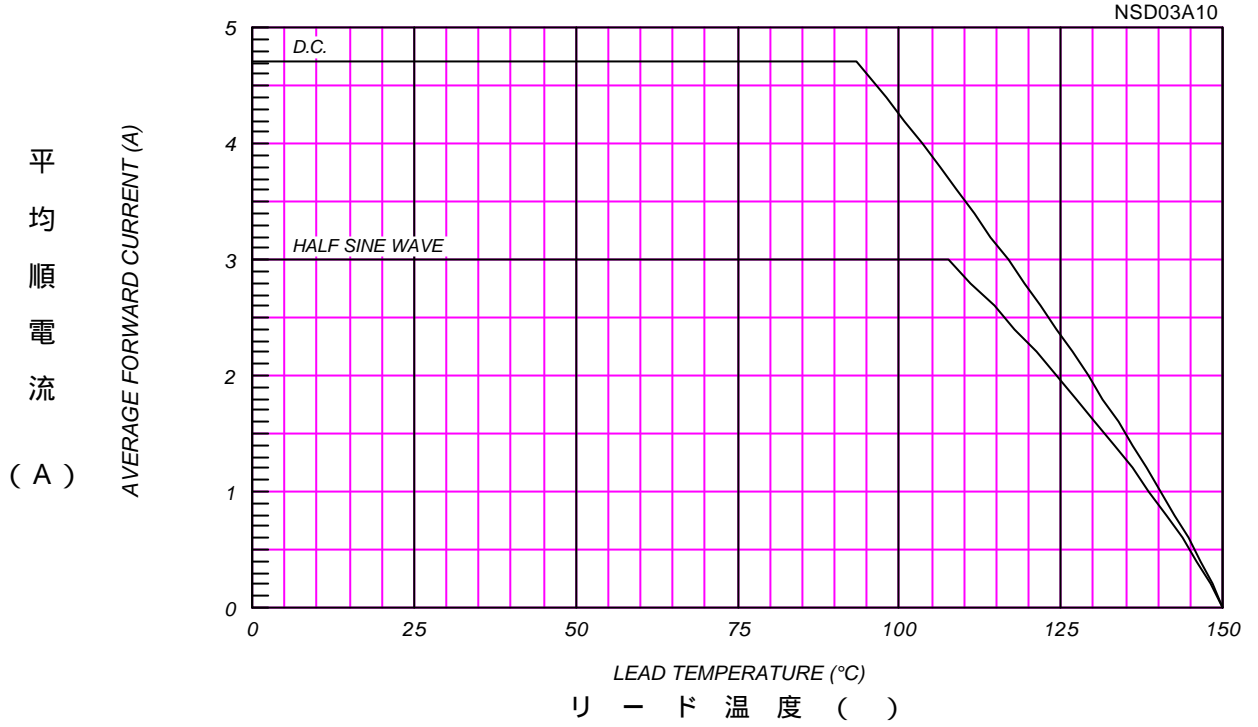
平均順電流 - 周圍溫度定格  
AVERAGE FORWARD CURRENT VS. AMBIENT TEMPERATURE

Glass-Epoxy Substrate Mounted(Soldering Land=2\*3.5mm)

NSD03A10



平均順電流 - リード温度定格  
 AVERAGE FORWARD CURRENT VS. LEAD TEMPERATURE



サージ順電流定格  
 SURGE CURRENT RATINGS

f=50Hz, Half Sine Wave, Non-Repetitive, No Load

